



TE Connectivity

Product Change Notification: P-25-028147
Customer: Newark Electronics (167839) Location: Chicago PCN Date: 14-MAY-25
Agreement: Agreement Unknown

TE would like to inform you of the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

General Product Description:
Multigig RT2, RT2-R, RT3 Daughtercard connectors with Differential wafers

Description of Changes

Current Differential Signal wafers have Gold plated ground pads strategically located on non-contact areas of the backside of the wafer. These pads are used for Impedance tuning of the Differential signal pairs on the opposite mating side of the wafer. The Gold and Nickel underplate over the Copper Ground pads will be replaced by extending the existing soldermask material to cover the non-contact areas. See attached photo. Samples have been tested both electrically and mechanically to verify they continue to meet the same performance and are compliant to the TE Product Specification.

wafer comparison



EXISTING DESIGN NEW DESIGN

Reason for Changes:	
Product improvement.This change contributes to our continued quality improvement, performance, and sustainability objectives.	
Estimated Dates:	
Last Order Date (Obsolete Parts Only):	First Date To Ship (Changed Parts Only):
	17-NOV-2025
Last Ship Date (Obsolete Parts Only):	Last Date for Mixed Shipments: (Changed Parts Only):
	13-FEB-2026

Part Number(s) being Modified:

Part Number	Part Discontinued per PCN	Customer Drawing	Customer Part Number	Alias Part Number(s)	Substitute Part Number	Substitute Alias Part Number(s)	Description Of Difference
2302785-1	NO						